

**AMENDMENTS TO THE SPECIFICATION**

Please replace the paragraph at Page 9, lines 3-17 with the following.

Referring now to FIG. 2, the imaging system 10 of FIG. 1 can be incorporated within an inspection system 250 to inspect features, such as solder joints and components, on a target surface 20 for quality control purposes. The inspection system 250 includes an illumination source 200 for illuminating a portion of the target surface 20 within the field of view (FOV) of the camera 100. The illumination source 50 can be an suitable source of illumination. For example, the illumination source ~~[[50]]~~200 can be include one or more light emitting elements, such as one or more point light sources, one or more collimated light sources, one or more illumination arrays, or any other illumination source suitable for use in inspection system 250. Illumination emitted from the illumination source ~~[[50]]~~200 is reflected by ~~[[øf]]~~ a portion of the target surface 20 and received by the camera 100. The reflected light (eg., IR and/or UV) is focused by optics 105 onto an image sensor 110, such as a CMOS sensor chip or a CCD sensor chip within the camera 100. The image sensor 110 includes a two-dimensional array of pixels 115 arranged in rows and columns. The pixels detect the light reflected from the target surface 20 and produce raw image data representing an image of the target surface 20.